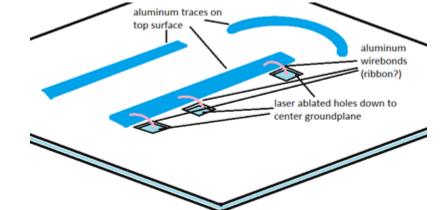


## Summary and Outlook from May 9, 2024

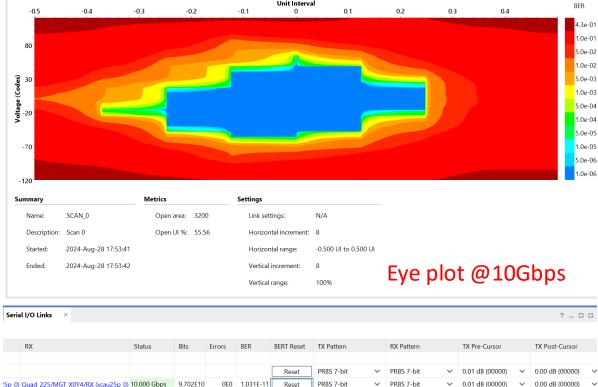
- First low TRL prototypes produced by Omni and evaluated
  - Based on a PCB design from another project
  - Ok for wire-bonding but not soldering
  - Significant signal loss at high frequency
- Second iteration is being worked on
  - Dedicated for signal transmission investigation to understand and improve signal losses: different substrate materials, different width/pitch, with and without soldering mask
  - Make use of selective Cu plating for soldering, and wire-bonding to connect top and bottom
  - Make plated-thru holes in an all-aluminum stack





## **Updates for Today**

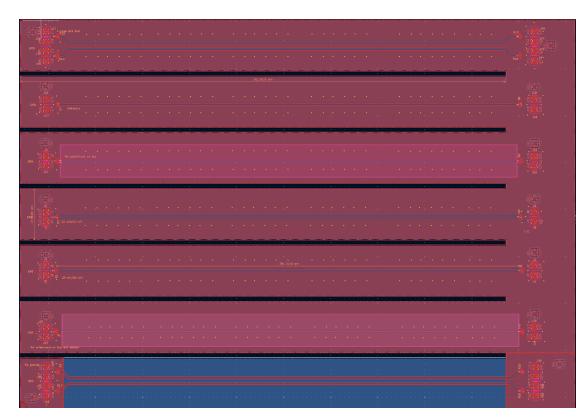
- Received a 2nd set of Al-based FPC prototypes from OMNI.
  - Double metal layer with 25 cm long differential lines for high-speed data transmission
- Improvements compared to the previous set
  - Soldering and vias facilitated by selective Cu plating
  - Improved high frequency signal transmission property based on S21 measured up to 4 GHz
  - IBERT test done with FPGA suggests that these FPC support GTY communication @10Gbps
- Questions to follow up:
  - Check the mechanical properties of the FPC
  - 2 out of 36 connector pads detached from the FPC when disconnecting the cable
  - Total material budget of the FPC is 0.136%  $X_0$  (TBC), with dominant contribution from dielectrics. Can this be reduced
- Plan:
  - Manufacture FPC based on LTU/STFC design but modified to be consistent with vendor's design rules if there is no objection.





## **Updates for Today**





## The photo of Aluminum FPC

The layout of FPC